

## **AMENDMENTS TO THE CLAIMS**

This listing of claims will replace all prior versions and listings of claims in the application.

### **Listing of Claims:**

1. (Original) A method for mutually welding a plate that has at least one layer based on Ag alloys and a copper body, comprising the use of laser means for performing said welding, characterized in that it comprises the steps that consist in:
  - superimposing and coupling one face of said plate on a surface of said copper body;
  - starting the welding process by focusing the laser means on a point located proximate to the joint between said face of said plate and said surface of said copper body;
  - maintaining an angle of incidence of said laser means at values other than 0° with respect to the perpendicular to the surface to be welded;
  - moving the laser means with respect to the joint, so that the weldpool is pushed along the joint.
2. (Original) The method for mutually welding a plate and a copper body according to claim 1, characterized in that said starting occurs by focusing the laser means on a point of the copper body proximate to the joint between the surface of said copper body and the face of said plate.
3. (Original) The method for mutually welding a plate and a copper body according to claim 1, characterized in that the angle of incidence of said laser means with respect to the perpendicular to the surface to be welded is between 5 and 20°.

4. (Currently amended) The method for mutually welding a plate and a copper body according to ~~one or more of the preceding claims~~ claim 1, characterized in that at least 70% of the molten material lies, with respect to the joint, on the side that belongs to the copper body.
5. (Currently amended) The method for mutually welding a plate and a copper body according to ~~one or more of the preceding claims~~ claim 1, characterized in that said laser means comprise a solid-state laser.
6. (Currently amended) The method for mutually welding a plate and a copper body according to ~~one or more of the preceding claims~~ claim 1, characterized in that said plate comprises at least one layer based on alloys of Ag and at least one copper layer.
7. (Original) The method according to claim 6, characterized in that the copper layer of said plate constitutes the face of the plate that is superimposed and coupled on the copper body.
8. (Currently amended) The contact element obtained with a method according to ~~one or more of the preceding claims~~ claim 1.
9. (Original) The contact element according to claim 8, characterized in that said copper body is the moving contact of a low-voltage contactor or circuit breaker.
10. (Original) The contact element according to claim 8, characterized in that said copper body is the fixed contact of a low-voltage contactor or circuit breaker.
11. (Currently amended) A low-voltage circuit breaker, characterized in that it comprises one or more contact elements according to ~~one of claims 8 and~~ claim 9.
12. (Currently amended) A low-voltage contactor, characterized in that it comprises one or more contact elements according to ~~one of claims 8 or~~ claim 9.

13. (New) The method for mutually welding a plate and a copper body according to claim 2 characterized in that at least 70% of the molten material lies, with respect to the joint, on the side that belongs to the copper body.
14. (New) The method for mutually welding a plate and a copper body according to claim 3 characterized in that at least 70% of the molten material lies, with respect to the joint, on the side that belongs to the copper body.
15. (New) The method for mutually welding a plate and a copper body according to claim 2, characterized in that said laser means comprise a solid-state laser.
16. (New) The method for mutually welding a plate and a copper body according to claim 3, characterized in that said laser means comprise a solid-state laser.
17. (New) The method for mutually welding a plate and a copper body according to claim 4, characterized in that said laser means comprise a solid-state laser.
18. (New) The method for mutually welding a plate and a copper body according to claim 2, characterized in that said plate comprises at least one layer based on alloys of Ag and at least one copper layer.
19. (New) The method for mutually welding a plate and a copper body according to claim 3, characterized in that said plate comprises at least one layer based on alloys of Ag and at least one copper layer.
20. (New) The method for mutually welding a plate and a copper body according to claim 4, characterized in that said plate comprises at least one layer based on alloys of Ag and at least one copper layer.